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**INITIAL PRODUCT/PROCESS CHANGE NOTIFICATION #20637**Generic Copy

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**Issue Date:** 09-Sep-2014**TITLE:** Additional Assembly manufacture site for LE25U40CMCSxx & LE25U40CMCQxx series**PROPOSED FIRST SHIP DATE:** 09-Jan-2015**AFFECTED CHANGE CATEGORY(S):** Product site Addition**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**

Contact your local ON Semiconductor Sales Office or  
< [Ai-Ling.Loh@Onsemi.com](mailto:Ai-Ling.Loh@Onsemi.com) > or < [Karl.Hill@onsemi.com](mailto:Karl.Hill@onsemi.com) >

**NOTIFICATION TYPE:**

Initial Product/Process Change Notification (IPCN)

First change notification sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.

The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN).

This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change.

**DESCRIPTION AND PURPOSE:**

This change is addition of the back-end manufacturing site for LE25U40CMC series produced in Amkor Philippines. The addition of this production factory enables stable timely product supply.

There is no characteristic change to use same DIE. Assembly and testing site change from Amkor Philippines to ON Semiconductor Philippines, Inc. (OSPI).

OSPI has actual production of the flash memory using the similar package. Package materials except mold resin are changed. But OSPI have the experience of the material in other flash memory. Therefore there is no risk by this change.


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**QUALIFICATION PLAN:**

Estimated Date for Qualification Completion: September /30 / 2014  
 Samples should be available after completion of Qualification.

Test Item	Test Condition	Test Time	N
Temperature Humidity Bias	Ta = 85C, RH=85%, Bais = 4.6V	1000h	77 x 3
High Temperature Storage	Temp = +150°C	1000h	77 x 3
Temperature Cycle	Temp = -65°C to +150°C;	1000c	77 x 3
Pressure Cooker	121°C/100% RH/15 PSIG	200h	77 x 3
PC (MSL1 Preconditioning)	IR Reflow: Sanyo original method. Bake (Ta=125 deg C/24h) -> Soak (85 deg C, 85%RH/168h) ->Reflow 3time (Profile : JEDEC)	-	240 x 3
SAT(MSL)	SAT -> Bake -> Moisture Sork ->IR refloe -> SAT ->E-test	-	22 x 3

**List of affected Parts:**

LE25U40CMCQ00-AH  
 LE25U40CMCS00-AH  
 LE25U40CMCQ02-AH  
 LE25U40CMCQ03-AH  
 LE25U40CMCQ04-AH  
 LE25U40CMCQ05-AH  
 LE25U40CMCQ06-AH  
 LE25U40CMCQ07-AH  
 LE25U40CMCQ08-AH  
 LE25U40CMCQ09-AH  
 LE25U40CMCS01-AH  
 LE25U40CMCS02-AH  
 LE25U40CMCS03-AH